Product Envr-Stewards Requester Item Number Mfr Item Nu	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name* Company unique ID Unique ID Authority Response Date* 2023-06-08 Contact Name Product Env-Stewards ITitle - Contact* Product Env-Stewards ITitle - Representative* Title - Representative Product Enviro Compliance ITitle - Representative NA Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards Product Env-Stewards NA NCP302LSN09TIG ANA UNDERVOLT DETECT 0.9V 2023-06-08 Manufacturing Site Weight* UOM Unit I NCP302LSN09TIG ANA UNDERVOLT DETECT 0.9V 2023-06-08 MAY1 14.08 mg Each Manufacturing Process Information Marufacturing Site Weight* UOM Unit I NATIONAL Marufacturing Site Weight* UOM Unit I NATIO	752-21.1											als and Mf	g Informati	on	
Semilar Semi	upplier Informa	ation						·							
Title - Contact Name Product Envis Compliance NA Na Naufacturing Site Weight* UOM Unit T NA Naufacturing Process Information Manufacturing Process Information Manufacturing Process Information Matte Tin (Sn) - annealed OUAlloy 1 260 C 30 Seconds NA Winder Email - Contact* Product-Env-Stewards ©onsemi.com NA Naufacturing Site Weight* UOM Unit T Naufacturing Site Naufacturing Site Naufacturing Site Naufacturing Site Naufacturing Site Naufacturing Process Information Manufacturing Process Information Manufacturing Process Information Matter Tin (Sn) - annealed OUAlloy 1 260 C 30 Seconds 3 Naufacturing Site	Company name* Company unique ID					J	Unique ID Authority					Response Date*			
Product-Env-Stewards Authorized Representative* Title - Representative Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Product-Env-St	nsemi											2023-06-0	08		
Authorized Representative* Product-Env-Stewards Product Enviro Compliance Product-Env-Stewards Product Enviro Compliance Product Enviro Compliance NA Product-Env-Stewards Produc	Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product Envi-Stewards Requester Item Number Mfr Item Nu	Product-Env-Stewar	rds		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Authorized Representative* Title				Fitle - Representative			Phone - Representative*			Email - Representative*				
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds Terminal Plating soldering is 10-30 seconds	Product-Env-Stewar	rds	Product Enviro Compliance			1	NA NA				Product-Env-Stewards@onsemi.com				
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds Somments Evel 1 - maximum time at peak temperature during soldering is 10-30 seconds	Requester	Requester Item Number Mf		Ifr Item Number Mfr Item Name				Effective Date	Version	Version Manufacturing Site		W	/eight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles 260 Comments Evel 1 - maximum time at peak temperature during soldering is 10-30 seconds			NCP302I	LSN09T1G	ANA UNDERVOL	T DETECT 0.	9V	2023-06-08		N	Л Ү1	14	4.08	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 omments vel 1 - maximum time at peak temperature during soldering is 10-30 seconds				arminal Reso	Alloy	STD 020 MSI	Pating	Dank Prog	ease Rody 7	Camparatur	May Time at Pools	Tamparatu	ra Numb	ar of Paflow Cyc	Jac
Comments evel 1 - maximum time at peak temperature during soldering is 10-30 seconds					Alloy J-1	31D-020 MSL	, Kanng		ess body 1	T *				er of Reflow Cyc	ries
vel 1 - maximum time at peak temperature during soldering is 10-30 seconds	•	i (Sii) - aimealeu	C	U Alluy	1			200		IC	30	second	.5 3		
1 1 0 0		me at neak temperatura	during cal-	doring is 10-2	O seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a						
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of				
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted				
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose al applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the				

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.42	mg	Supplier	Silicon (Si)	7440-21-3		0.42	mg
Die Attach	0.11	mg	Supplier	Silver (Ag)	7440-22-4		0.088	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.022	mg
Lead Frame	5.78	mg	Supplier	Silver (Ag)	7440-22-4		0.0705	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0069	mg
			Supplier	Iron (Fe)	7439-89-6		0.1358	mg
			Supplier	Copper (Cu)	7440-50-8		5.565	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0017	mg
Mold Compound-Black	7.34	mg		Epoxy resin	proprietary data		0.367	mg
			Supplier	Phenolic Resin	Proprietary Data		0.367	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.1468	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0367	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.4225	mg
Plating	0.39	mg	Supplier	Tin (Sn)	7440-31-5		0.39	mg
Wire Bond - Au	0.04	mg	Supplier	Gold (Au)	7440-57-5		0.04	mg